

L Number	Hits	Search Text	DB	Time stamp
1	4944	(438/455-459, 464, 479, 517, 149, 976-979).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 12:44
2	560	((438/455-459, 464, 479, 517, 149, 976-979).ccls.) and @pd>20020701	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 12:45
3	114	((substrate with (bond\$3 or laminat\$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant\$3 or implantation))) and (glass\$2 and quartz)	USPAT	2003/03/06 13:24
6	49	5494835.URPN.	USPAT	2003/03/06 13:34
7	135	split\$4 with ion with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:46
8	36	split\$4 with ion with wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:53
9	9	("4445965" "4582559" "4816420" "5273938" "5391257" "5397713" "5618739" "5670411" "5695557").PN.	USPAT	2003/03/06 13:49
10	2	("5744401" "5869387").PN.	USPAT	2003/03/06 13:50
11	1	6362076.URPN.	USPAT	2003/03/06 13:51
12	4100	(split\$4 or delaminat\$4 or separat\$5) with (ion or implant\$7) with (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:55
13	1079	((split\$4 or delaminat\$4 or separat\$5) with (ion or implant\$7) with (wafer or substrate)) and (mask with implant\$7)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 13:55
14	191	((split\$4 or delaminat\$4 or separat\$5) with (ion or implant\$7) with (wafer or substrate)) and (mask with implant\$7 with resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 14:01
15	17	mask with implant\$7 with resin with resist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 14:01